

## **US2ABF THRU US2MBF**

## **Surface Mount Ultrafast Recovery Rectifier FEATURES**

Reverse Voltage –  $50V\sim1000~V$ 

Forward Current – 2.0 A

• For surface mounted applications

• Low profile package

• Glass Passivated Chip Junction

• Superfast reverse recovery time

• Lead free in comply with EU RoHS 2011/65/EU directives

#### **MECHANICAL DATA**

• Case: SMBF

• Terminals: Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 57mg / 0.002oz

## **Maximum Ratings and Electrical characteristics**

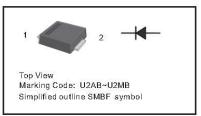
Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	US2ABF	US2BBF	US2DBF	US2GBF	US2JBF	US2KBF	US2MBF	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>rrm</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>pc</sub>	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Ta = 65 °C	I <sub>F(AV)</sub>	2							Α
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	55 50						А	
Maximum Instantaneous Forward Voltage at 2 A	V <sub>F</sub>	1.0 1.3			1.6		٧		
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I <sub>R</sub>				5 100				μA
Typical Junction Capacitance 13	C <sub>j</sub>				60				рF
Maximum Reverse Recovery Time 2>	t,,	50 75				ทธ			
Typical Thermal Resistance 3>	Reja Reji	60 20						°C/W	
Operating and Storage Temperature Range	Tj, Tstg	-55~+150							°C

<sup>1 )</sup> Measured at 1 MHz and applied reverse voltage of 4 V D.C  $\,$  2 ) Measured with IF = 0.5 A, IR = 1 A, Irr = 0.25 A

**PINNING** 

PIN	DESCRIPTION	9
1	Cathode	76
2	2 Anode	



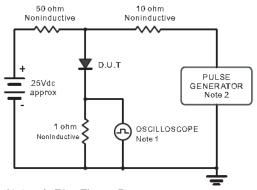
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<sup>3</sup> ) P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7  $mm_{\mbox{\tiny 2}})$  copper pad areas.

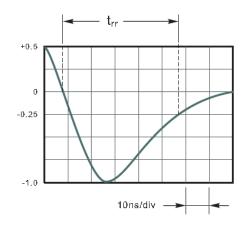


## **US2ABF THRU US2MBF**

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



- Note: 1. Rise Time = 7ns, max. Input Impedance = 1megohm,22pF.
  - Ries Time =10ns, max.Source Impedance = 50 ohms.



Set time Base for 10ns/div



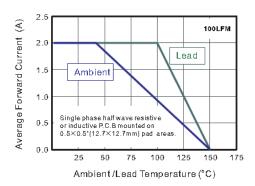


Fig.3 Typical Reverse Characteristics

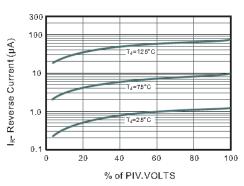


Fig.3 Typical Instaneous Forward Characteristics

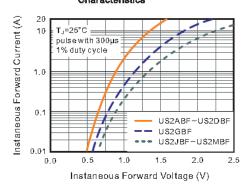
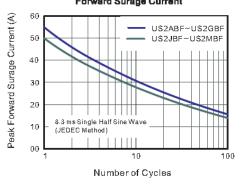


Fig.4 Maximum Non-Repetitive Peak Forward Surage Current



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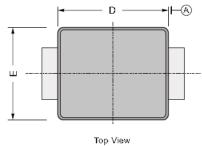
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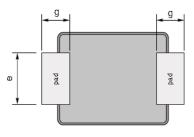
**SMBF** 

### **PACKAGE OUTLINE**

Plastic surface mounted package; 2 leads

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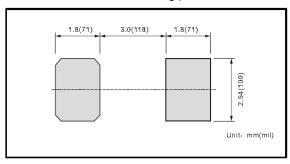




W Bottom View

UNIT		Α	С	D	Е	H <sub>E</sub>	е	g	2
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	· 9°
	min	1.1	0.18	4.2	3.5	5.1	1.9	1.0	
mil	max	51	10	173	146	216	86	40	
	min	43	7	165	138	200	75	40	

### The recommended mounting pad size



## Marking

Type number	Marking code				
US2ABF	U2AB				
US2BBF	U2BB				
US2DBF	U2DB				
US2GBF	U2GB				
US2JBF	U2JB				
US2KBF	U2KB				
US2MBF	U2MB				

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